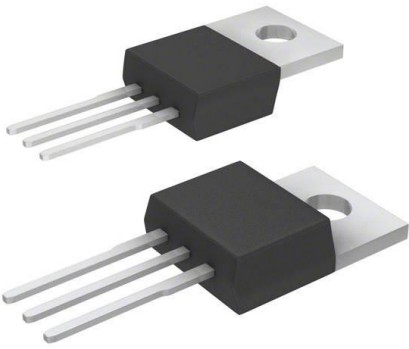


BTS113ANKSA1 Datasheet

www.digi-electronics.com



<https://www.DiGi-Electronics.com>

DiGi Electronics Part Number	BTS113ANKSA1-DG
Manufacturer	Infineon Technologies
Manufacturer Product Number	BTS113ANKSA1
Description	MOSFET N-CH 60V 11.5A TO220AB
Detailed Description	N-Channel 60 V 11.5A (Tc) 40W (Tc) Through Hole T O-220AB



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

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Purchase and inquiry

Manufacturer Product Number:

BTS113ANKSA1

Series:

TEMPFET®

FET Type:

N-Channel

Drain to Source Voltage (Vdss):

60 V

Drive Voltage (Max Rds On, Min Rds On):

4.5V

Vgs(th) (Max) @ Id:

2.5V @ 1mA

Input Capacitance (Ciss) (Max) @ Vds:

560 pF @ 25 V

Power Dissipation (Max):

40W (Tc)

Mounting Type:

Through Hole

Package / Case:

TO-220-3

Manufacturer:

Infineon Technologies

Product Status:

Obsolete

Technology:

MOSFET (Metal Oxide)

Current - Continuous Drain (Id) @ 25°C:

11.5A (Tc)

Rds On (Max) @ Id, Vgs:

170mOhm @ 5.8A, 4.5V

Vgs (Max):

±10V

FET Feature:

-

Operating Temperature:

-55°C ~ 150°C (TJ)

Supplier Device Package:

TO-220AB

Environmental & Export classification

RoHS Status:

RoHS non-compliant

REACH Status:

REACH Unaffected

HTSUS:

8541.29.0095

Moisture Sensitivity Level (MSL):

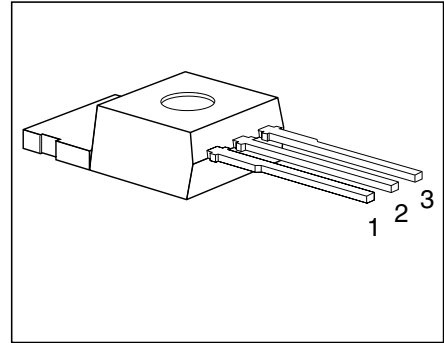
1 (Unlimited)

ECCN:

EAR99

Features

- N channel
- Logic level
- Enhancement mode
- Temperature sensor with thyristor characteristic
- The drain pin is electrically shorted to the tab



Pin	1	2	3
	G	D	S

Type	V_{DS}	I_D	$R_{DS(on)}$	Package	Ordering Code
BTS 113A	60 V	11.5 A	0.17 Ω	TO-220AB	C67078-S5015-A2

Maximum Ratings

Parameter	Symbol	Values	Unit
Drain-source voltage	V_{DS}	60	V
Drain-gate voltage, $R_{GS} = 20 \text{ k}\Omega$	V_{DGR}	60	
Gate-source voltage	V_{GS}	± 10	
Continuous drain current, $T_C = 25 \text{ }^\circ\text{C}$	I_D	11.5	A
ISO drain current $T_C = 85 \text{ }^\circ\text{C}$, $V_{GS} = 10 \text{ V}$, $V_{DS} = 0.5 \text{ V}$	I_{D-ISO}	2.2	
Pulsed drain current, $T_C = 25 \text{ }^\circ\text{C}$	$I_{D \text{ puls}}$	46	
Short circuit current, $T_j = -55 \dots +150 \text{ }^\circ\text{C}$	I_{SC}	27	
Short circuit dissipation, $T_j = -55 \dots +150 \text{ }^\circ\text{C}$	P_{SCmax}	400	W
Power dissipation	P_{tot}	40	
Operating and storage temperature range	T_j , T_{stg}	$-55 \dots +150$	$^\circ\text{C}$
DIN humidity category, DIN 40 040	–	E	–
IEC climatic category, DIN IEC 68-1	–	55/150/56	
Thermal resistance			K/W
Chip-case	$R_{th \text{ JC}}$	≤ 3.1	
Chip-ambient	$R_{th \text{ JA}}$	≤ 75	



Electrical Characteristics

at $T_j = 25\text{ °C}$, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

Static Characteristics

Drain-source breakdown voltage $V_{GS} = 0, I_D = 0.25\text{ mA}$	$V_{(BR)DSS}$	60	–	–	V
Gate threshold voltage $V_{GS} = V_{DS}, I_D = 1\text{ mA}$	$V_{GS(th)}$	1.6	2.0	2.5	
Zero gate voltage drain current $V_{GS} = 0\text{ V}, V_{DS} = 60\text{ V}$	I_{DSS}				μA
		$T_j = 25\text{ °C}$	0.1	1.0	
		$T_j = 125\text{ °C}$	10	100	
Gate-source leakage current $V_{GS} = \pm 20\text{ V}, V_{DS} = 0$	I_{GSS}				
		$T_j = 25\text{ °C}$	10	100	nA
		$T_j = 150\text{ °C}$	2	4	μA
Drain-source on-state resistance $V_{GS} = 4.5\text{ V}, I_D = 5.8\text{ A}$	$R_{DS(on)}$	–	0.14	0.17	Ω

Dynamic Characteristics

Forward transconductance $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}, I_D = 5.8\text{ A}$	g_{fs}	4.5	7.5	–	S
Input capacitance $V_{GS} = 0, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	C_{iss}	–	420	560	pF
Output capacitance $V_{GS} = 0, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	C_{oss}	–	160	250	
Reverse transfer capacitance $V_{GS} = 0, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	C_{rss}	–	60	110	
Turn-on time t_{on} , ($t_{on} = t_{d(on)} + t_r$) $V_{CC} = 30\text{ V}, V_{GS} = 5.0\text{ V}, I_D = 3.0\text{ A},$ $R_{GS} = 50\text{ }\Omega$	$t_{d(on)}$	–	15	25	ns
	t_r	–	55	80	
Turn-off time t_{off} , ($t_{off} = t_{d(off)} + t_f$) $V_{CC} = 30\text{ V}, V_{GS} = 5.0\text{ V}, I_D = 3.0\text{ A},$ $R_{GS} = 50\text{ }\Omega$	$t_{d(off)}$	–	45	60	
	t_f	–	40	55	

**Electrical Characteristics** (cont'd)at $T_j = 25\text{ °C}$, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

Reverse Diode

Continuous source current	I_S	–	–	11.5	A
Pulsed source current	I_{SM}	–	–	46	
Diode forward on-voltage $I_F = 11.5\text{ A}$, $V_{GS} = 0\text{ V}$	V_{SD}	–	1.3	1.6	V
Reverse recovery time $I_F = I_S$, $di_F/dt = 100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$	t_{rr}	–	60	–	ns
Reverse recovery charge $I_F = I_S$, $di_F/dt = 100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$	Q_{rr}	–	0.10	–	μC

Temperature Sensor

Forward voltage $I_{TS(on)} = 5\text{ mA}$, $T_j = -55 \dots +150\text{ °C}$ Sensor override, $t_p \leq 100\text{ }\mu\text{s}$ $T_j = -55 \dots +160\text{ °C}$	$V_{TS(on)}$	–	1.4	1.5	V
		–	–	10	
Forward current $T_j = -55 \dots +150\text{ °C}$ Sensor override, $t_p \leq 100\text{ }\mu\text{s}$ $T_j = -55 \dots +160\text{ °C}$	$I_{TS(on)}$	–	–	5	mA
		–	–	600	
Holding current, $V_{TS(off)} = 5.0\text{ V}$, $T_j = 25\text{ °C}$ $T_j = 150\text{ °C}$	I_H	0.05 0.05	0.3 0.2	0.5 0.3	
Switching temperature $V_{TS} = 5.0\text{ V}$	$T_{TS(on)}$	150	–	–	°C
Turn-off time $V_{TS} = 5.0\text{ V}$, $I_{TS(on)} = 2\text{ mA}$	t_{off}	0.5	–	2.5	μs



Examples for short-circuit protection

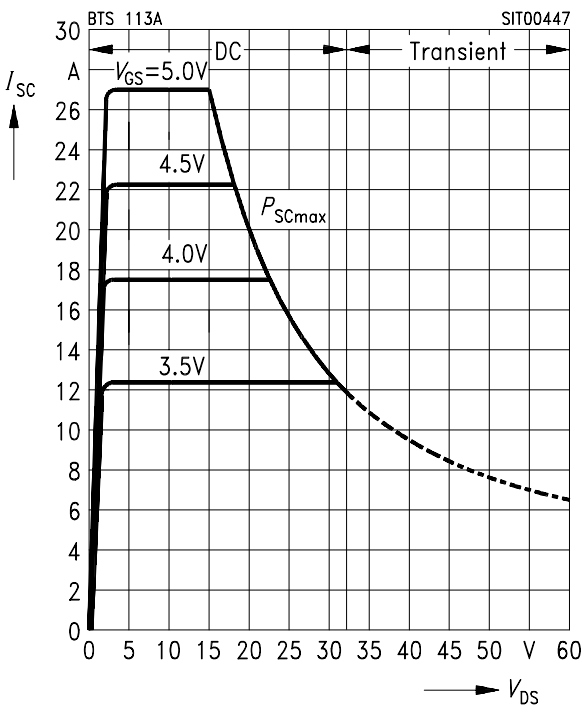
at $T_j = -55 \dots +150 \text{ }^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Examples			Unit
		1	2	–	
Drain-source voltage	V_{DS}	15	30	–	V
Gate-source voltage	V_{GS}	5.0	3.5	–	
Short-circuit current	I_{SC}	27	12.6	–	A
Short-circuit dissipation	P_{SC}	400	380	–	W
Response time $T_j = 25 \text{ }^\circ\text{C}$, before short circuit	$t_{SC(off)}$	20	20	–	ms

Short-circuit protection $I_{SC} = f(V_{DS})$

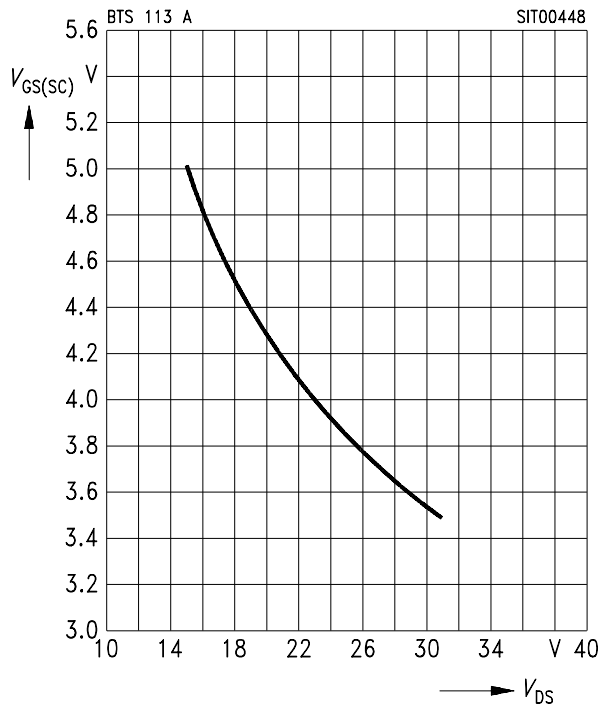
Parameter: V_{GS}

Diagram to determine I_{SC} for $T_j = -55 \dots +150 \text{ }^\circ\text{C}$



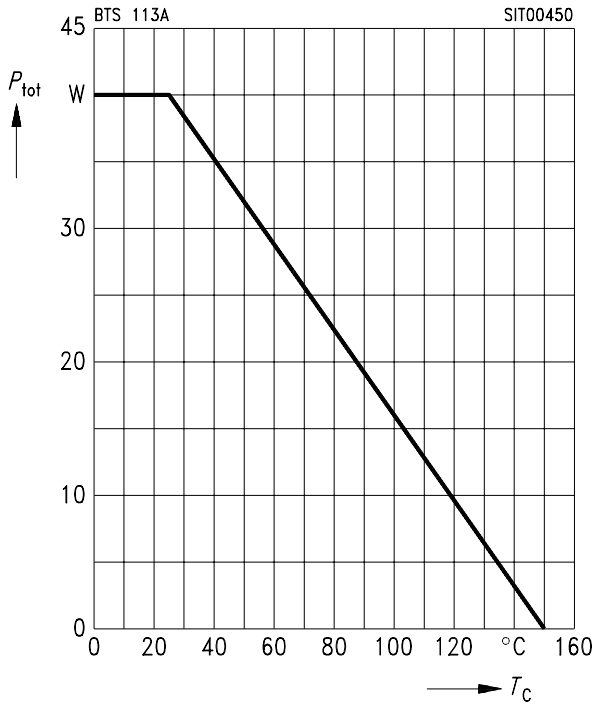
Max. gate voltage $V_{GS(SC)} = f(V_{DS})$

Parameter: $T_j = -55 \dots +150 \text{ }^\circ\text{C}$



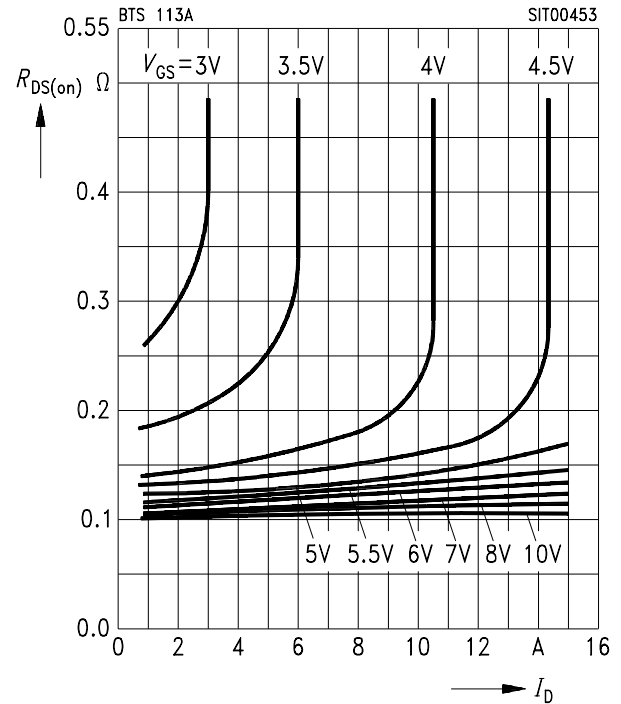


Max. power dissipation $P_{tot} = f(T_C)$



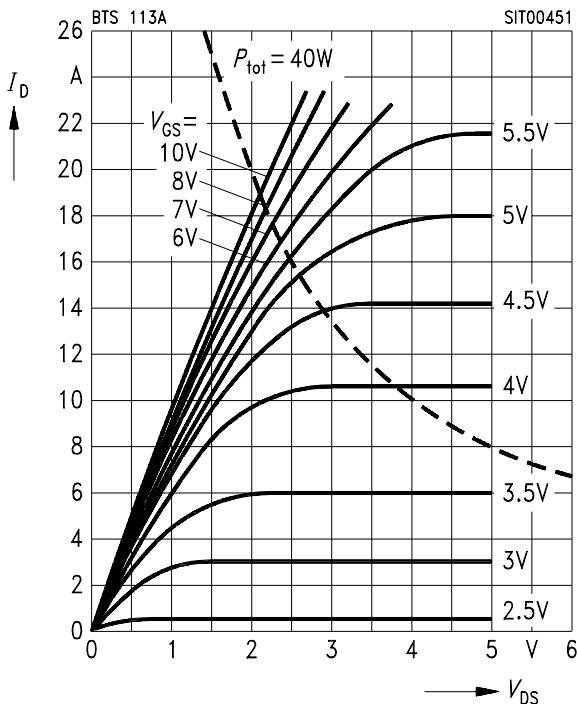
Typ. drain-source on-state resistance $R_{DS(on)} = f(I_D)$

Parameter: V_{GS}



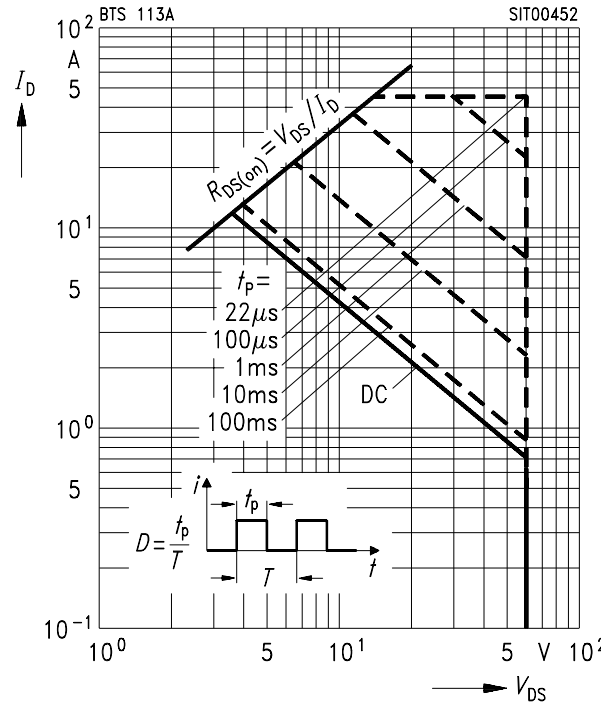
Typical output characteristics $I_D = f(V_{DS})$

Parameter: $t_p = 80 \mu s$



Safe operating area $I_D = f(V_{DS})$

Parameter: $D = 0.01, T_C = 25 \text{ }^\circ\text{C}$

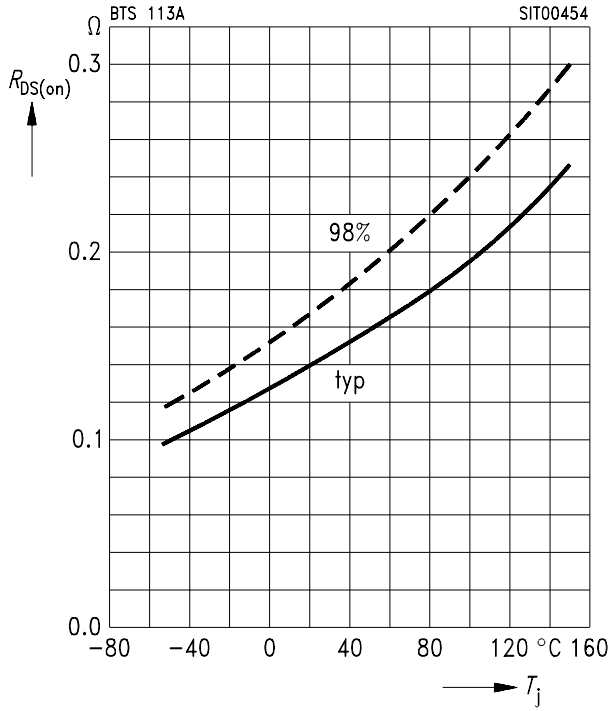




Drain-source on-state resistance

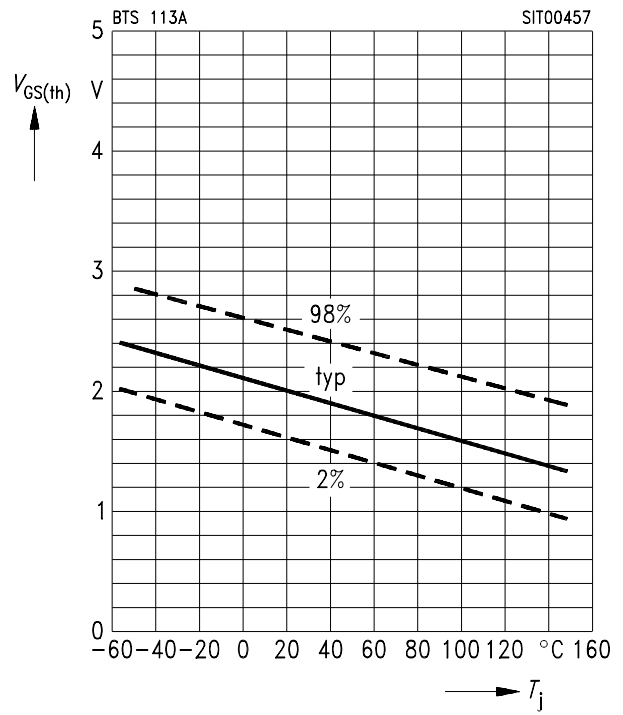
$R_{DS(on)} = f(T_j)$

Parameter: $I_D = -5\text{ A}$, $V_{GS} = 4.5\text{ V}$



Gate threshold voltage $V_{GS(th)} = f(T_j)$

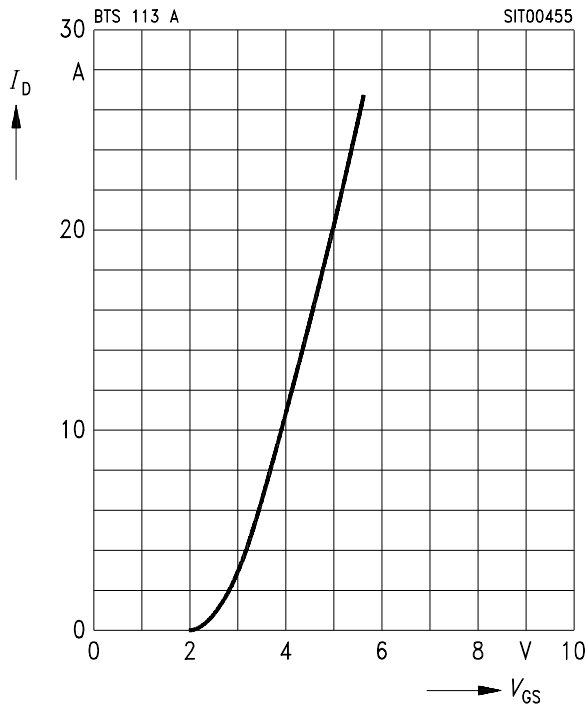
Parameter: $V_{DS} = V_{GS}$, $I_D = -1\text{ mA}$



Typ. transfer characteristic

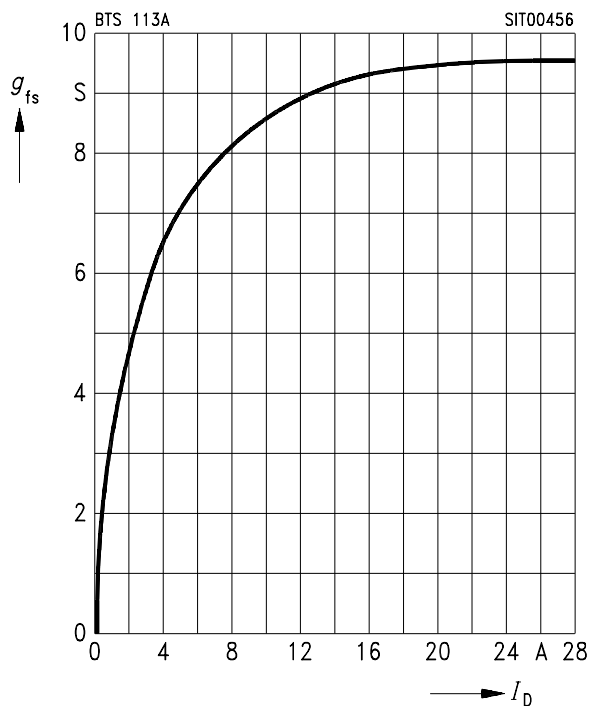
$I_D = f(V_{GS})$

Parameter: $t_p = 80\text{ }\mu\text{s}$, $V_{DS} = -25\text{ V}$



Typ. transconductance $g_{fs} = f(I_D)$

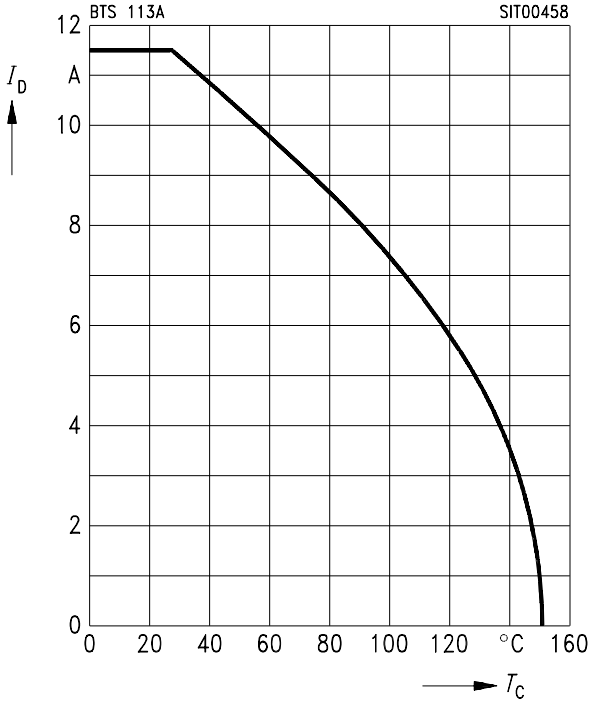
Parameter: $t_p = 80\text{ }\mu\text{s}$, $V_{DS} = -25\text{ V}$





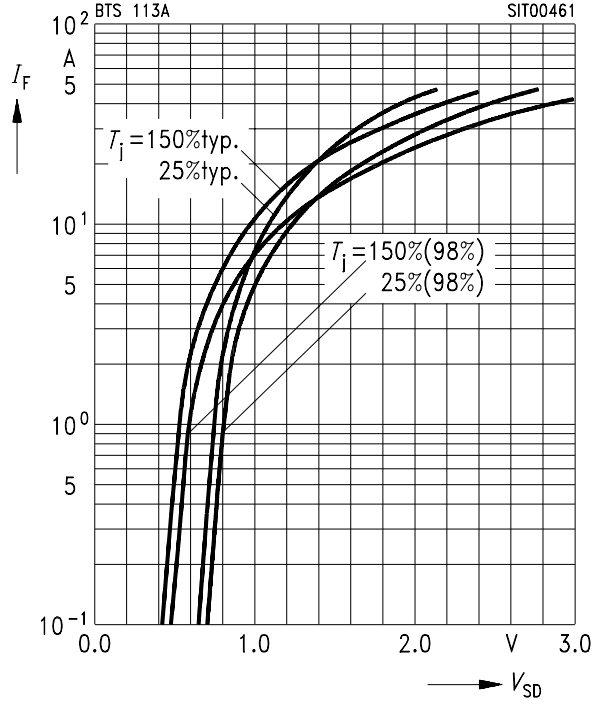
Continuous drain current $I_D = f(T_C)$

Parameter: $V_{GS} = 4.5 \text{ V}$



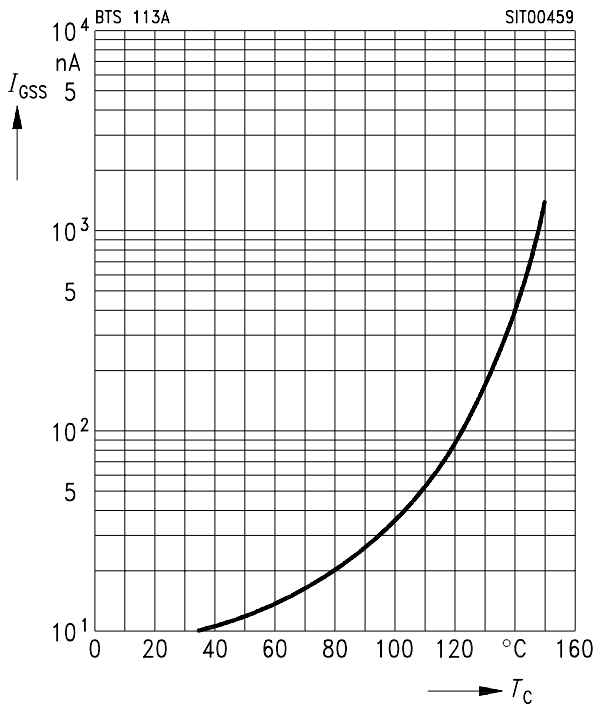
Forward characteristics of reverse diode $I_F = f(V_{SD})$

Parameter: $T_j, t_p = 80 \text{ s}$



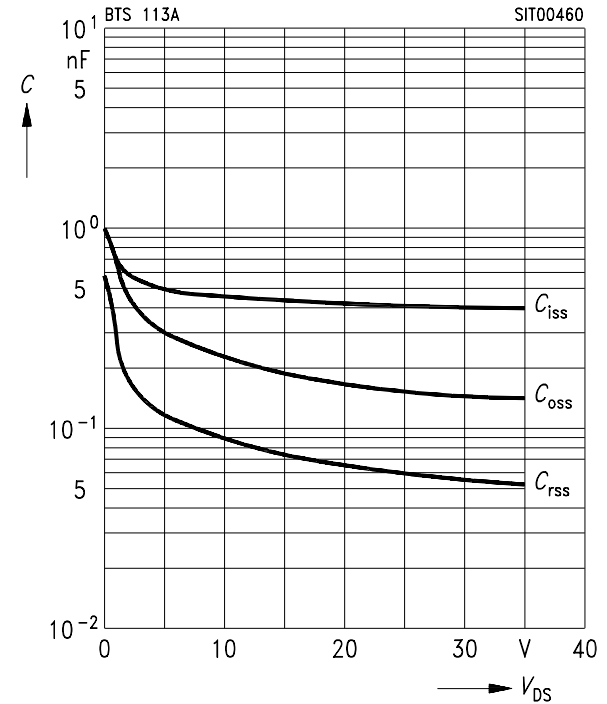
Typ. gate-source leakage current $I_{GSS} = f(T_C)$

Parameter: $V_{GS} = 10 \text{ V}, V_{DS} = 0$



Typ. capacitances $C = f(V_{DS})$

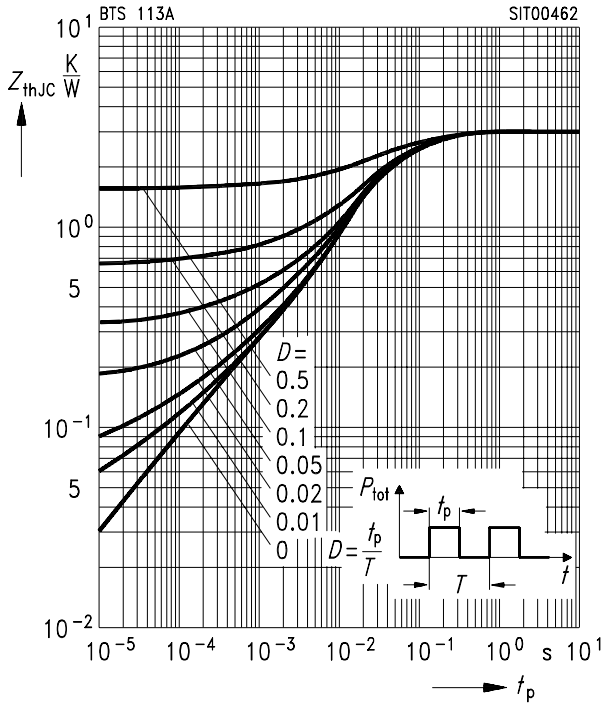
Parameter: $V_{GS} = 0, f = 1 \text{ MHz}$





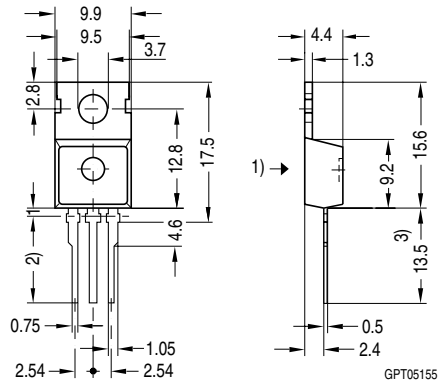
Transient thermal impedance $Z_{thJC} = f(t_p)$

Parameter: $D = t_p/T$



TO 220 AB
Standard

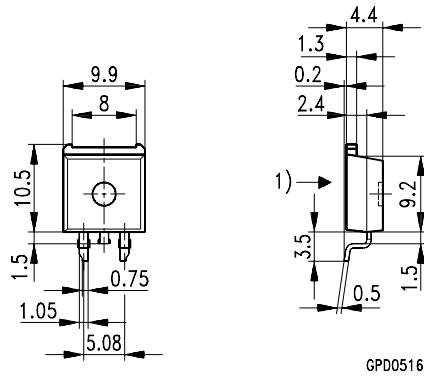
Ordering Code
C67078-S5015-A3



- 1) punch direction, burr max. 0.04
- 2) dip tinning
- 3) max. 14.5 by dip tinning press burr max. 0.05

TO 220 AB

SMD Version E 3045 A **Ordering Code**
(Tape & reel) C67078-S5015-A4



- 1) shear and punch direction no burrs this surface

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